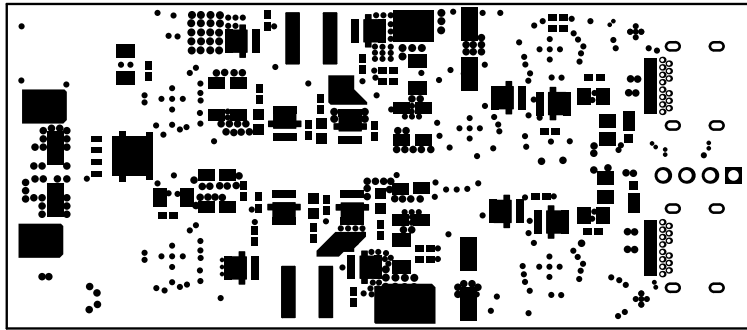
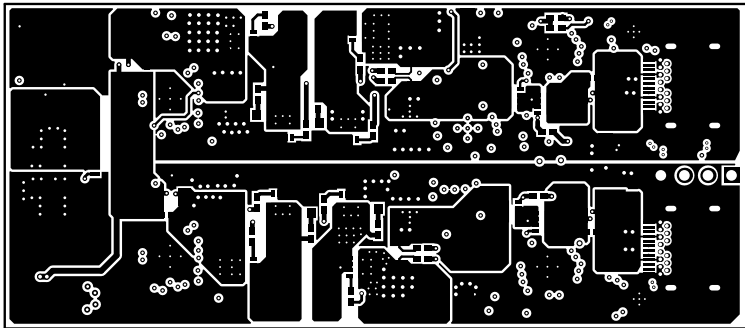


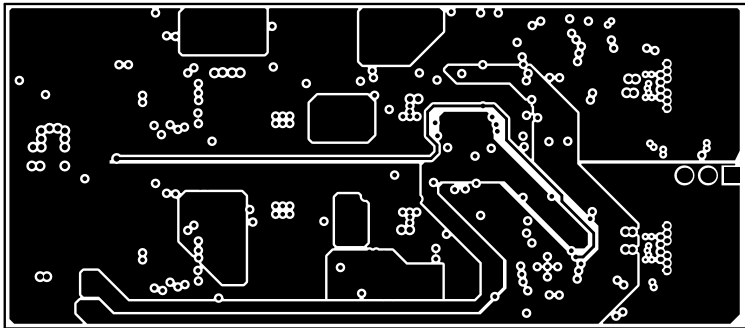
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40312	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP40312		
PLOT NAME = Top Overlay	GENERATED : 11/6/2017 10:42:33 AM	TEXAS INSTRUMENTS	



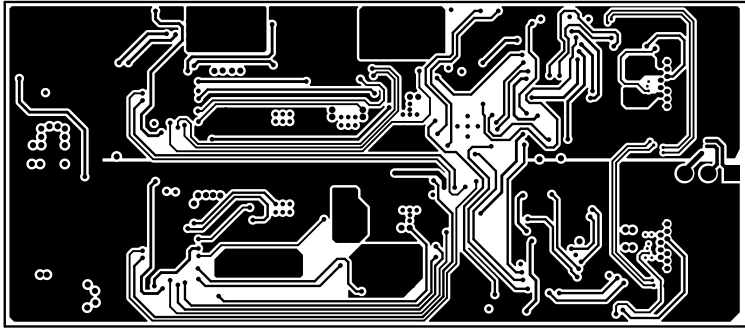
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40312	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP40312		
PLOT NAME = Top Solder Mask	GENERATED : 11/6/2017 10:42:34 AM	TEXAS INSTRUMENTS	



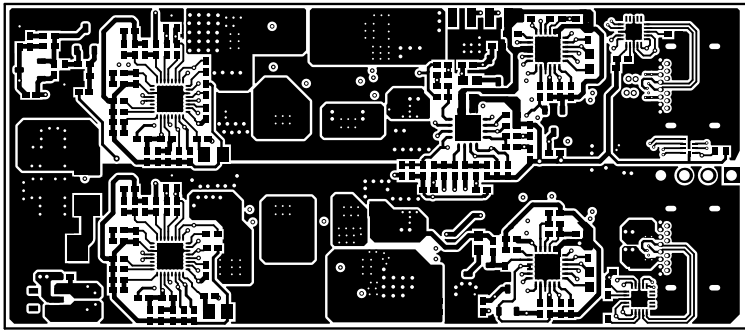
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40312	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP40312		
PLOT NAME = Top Layer	GENERATED : 11/6/2017 10:42:36 AM	TEXAS INSTRUMENTS	



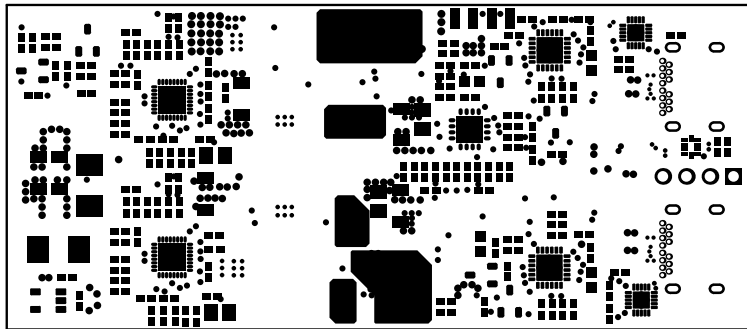
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40312	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: PMP40312		
PLOT NAME = Signal 1	GENERATED : 11/6/2017 10:42:37 AM	TEXAS INSTRUMENTS	



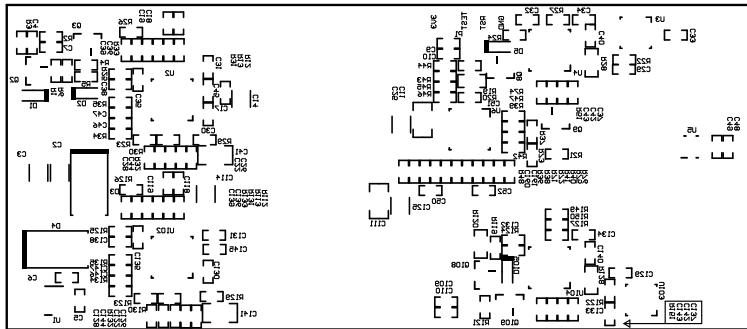
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40312	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: PMP40312		
PLOT NAME = Signal 2	GENERATED : 11/6/2017 10:42:39 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40312	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP40312		
PLOT NAME = Bottom Layer	GENERATED : 11/6/2017 10:42:40 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40312	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP40312		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/6/2017 10:42:42 AM	TEXAS INSTRUMENTS	

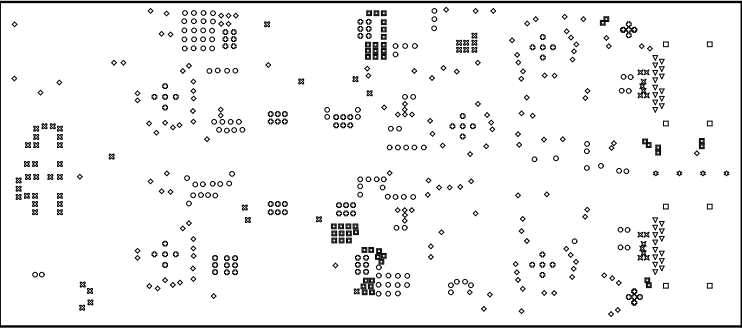


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40312	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP40312		
PLOT NAME = Bottom Overlay	GENERATED : 11/6/2017 10:42:43 AM	TEXAS INSTRUMENTS	

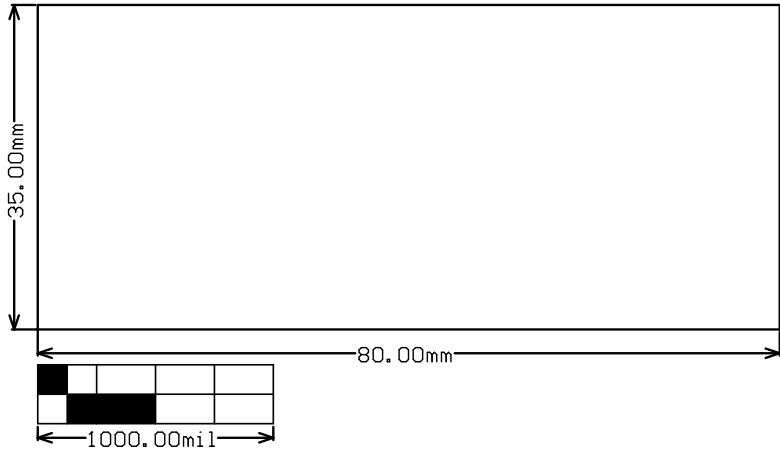


Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✕	14	6.00mil (0.152mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	90	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊞	48	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
◇	154	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	46	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
▽	28	15.75mil (0.400mm)	PTH	Round	Top Layer - Bottom Layer	
○	113	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	4	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
□	8	23.62mil (0.600mm)	PTH	Slot	Top Layer - Bottom Layer	
	505 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40312	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP40312		
PLOT NAME = Drill Drawing	GENERATED : 11/6/2017	10:42:45 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40312	REV: A	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP40312		
PLOT NAME = Board Dimensions	GENERATED : 11/6/2017 10:42:47 AM	TEXAS INSTRUMENTS	

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